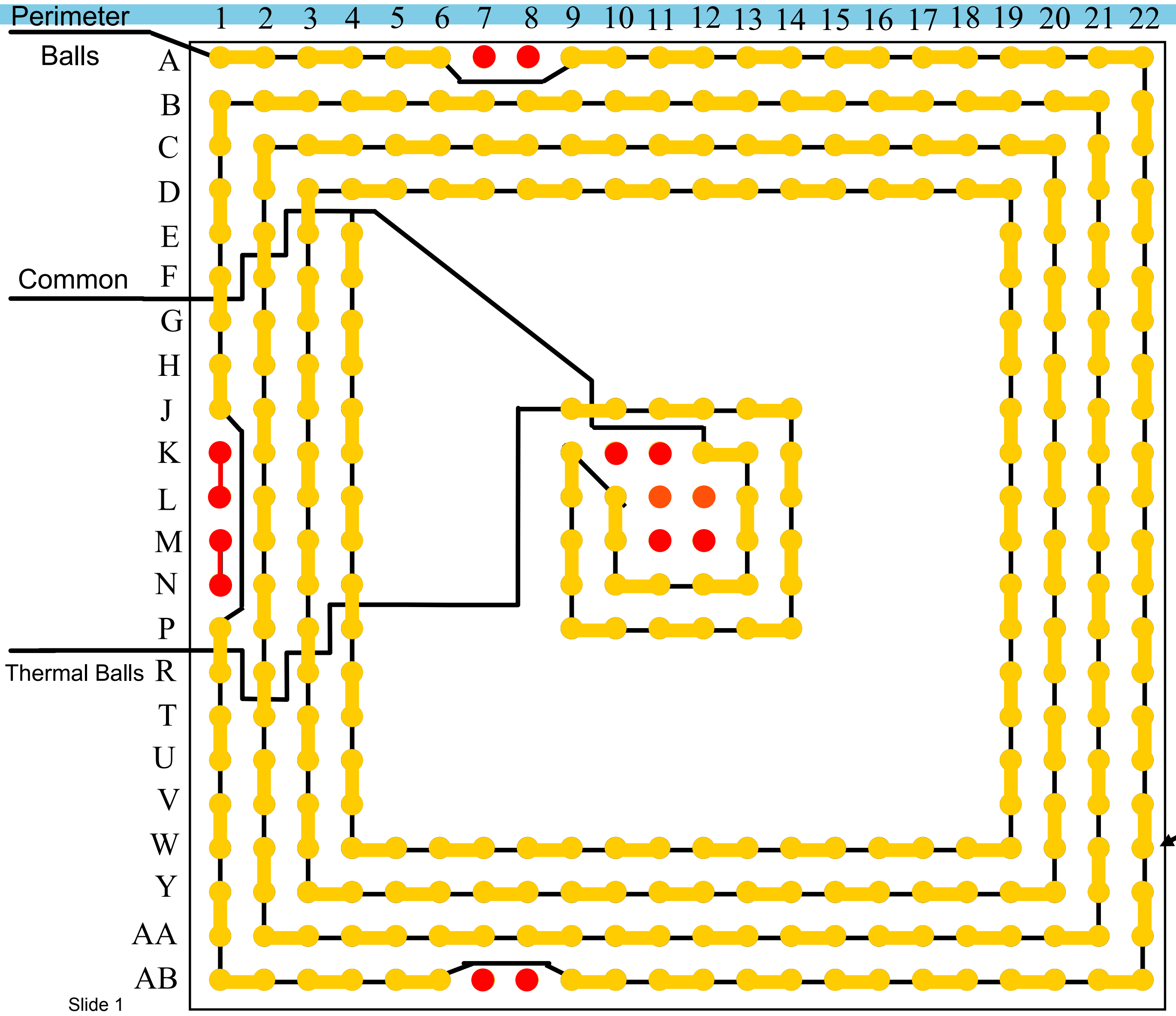
324 PBGA / TEPBGA Wire Bond Daisy Chain

Test Board and Package Traces: Looking Through Package and at Test Board



- * 1.0 mm Pitch
- * 22x22 Array (4 Row Perim)
- * 36 Thermal Balls
- * 23x23 mm Body Size
- * 0.5 mm Package Pad
- * 0.6 mm Solder Ball Diam.

— = Test Board Trace

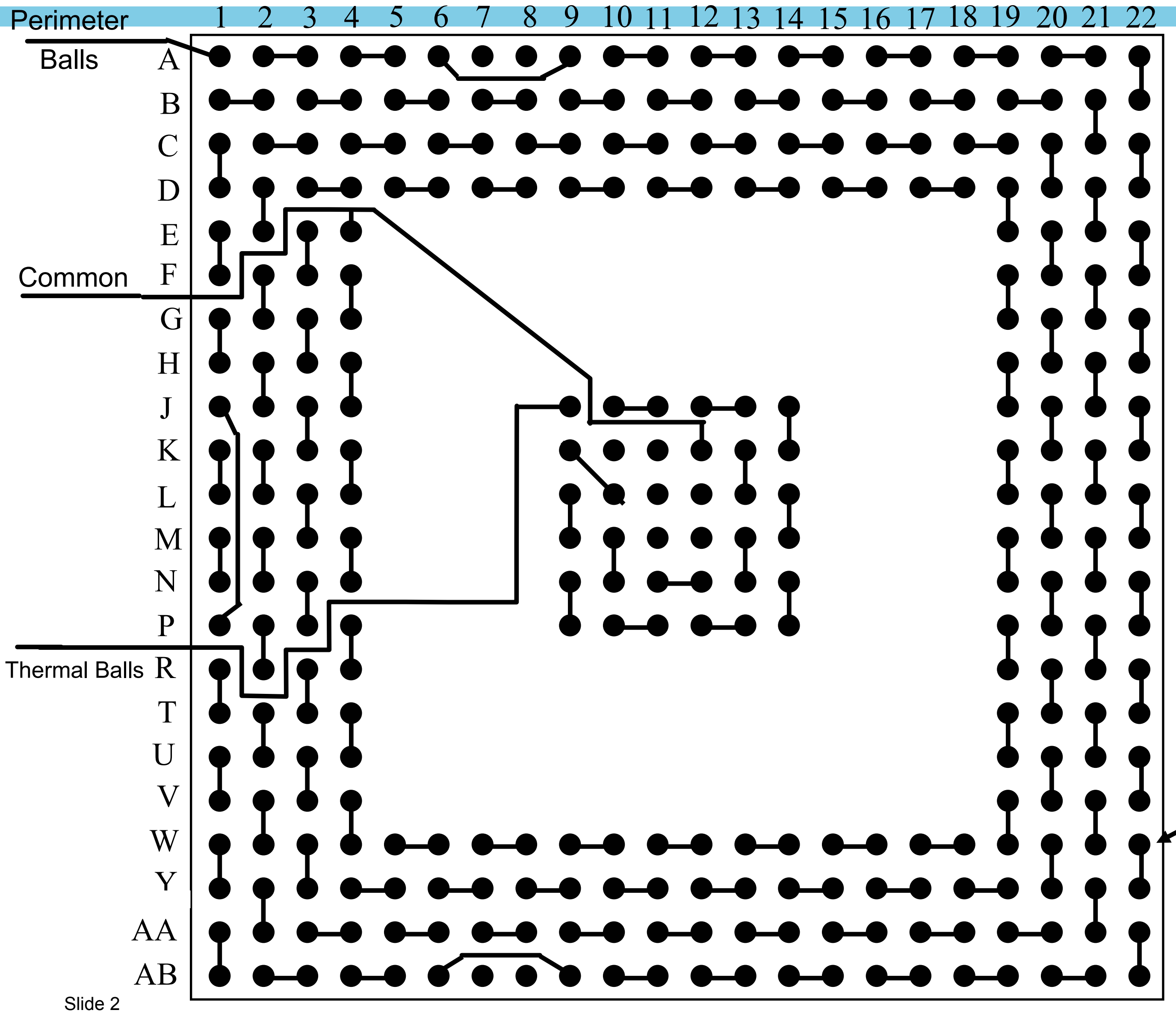
— = BGA Package Trace

● = Freescale Internal Use Only. Do not connect.

Non-Soldermask Defined Solder Pad Sizes of 0.48 mm Cu Diameter and 0.63mm solder mask opening.

gested Test Board for the 324 PBGA / TEPBGA Wire Bond Daisy Chain

Test Board Traces Only: Looking Through Package and at Test Board



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